

What is claimed is:

3/27/209  
11/6/01  
1. A thermal head comprising a substrate with a heater formed thereon, a driver IC mounted on said substrate for providing a drive signal for said heater, and an encapsulation portion for protecting said IC, wherein at least a part of said sealing portion has a surface cut in separation.

2. A thermal head as claimed in claim 1, wherein said surface cut in separation is cliff-shaped and the height of said cliff shape is 0.1 mm to 1.5 mm.

3. A thermal head as claimed in claim 1, wherein said distance between an electrode portion where said driver IC is electrically connected with said substrate and said surface cut in separation is 0.1 mm to 2.2 mm.

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4. A method for manufacturing from a large substrate a plurality of thermal heads comprising heaters, driver ICs for providing a drive signal for said heaters, and encapsulation for protecting said ICs comprising the steps of:

preparing a large substrate, a plurality of electrodes for mounting said driver ICs being laid out thereon symmetrically with respect to separating lines of thermal heads adjacent to each other;

mounting said driver ICs on said electrodes for mounting said driver ICs;

filling with encapsulation resin IC mounting portions of a plurality of thermal heads adjacent to each other on said large substrate;

~~forming grooves in at least one of encapsulation resin~~

portions and the back of said substrate; and

separating said substrate into individual thermal heads  
using said grooves.

5. A method for preparing thermal heads as claimed in claim 4,  
wherein in said step of forming grooves, said grooves are formed  
~~only in the back of said substrate with laser scribing.~~